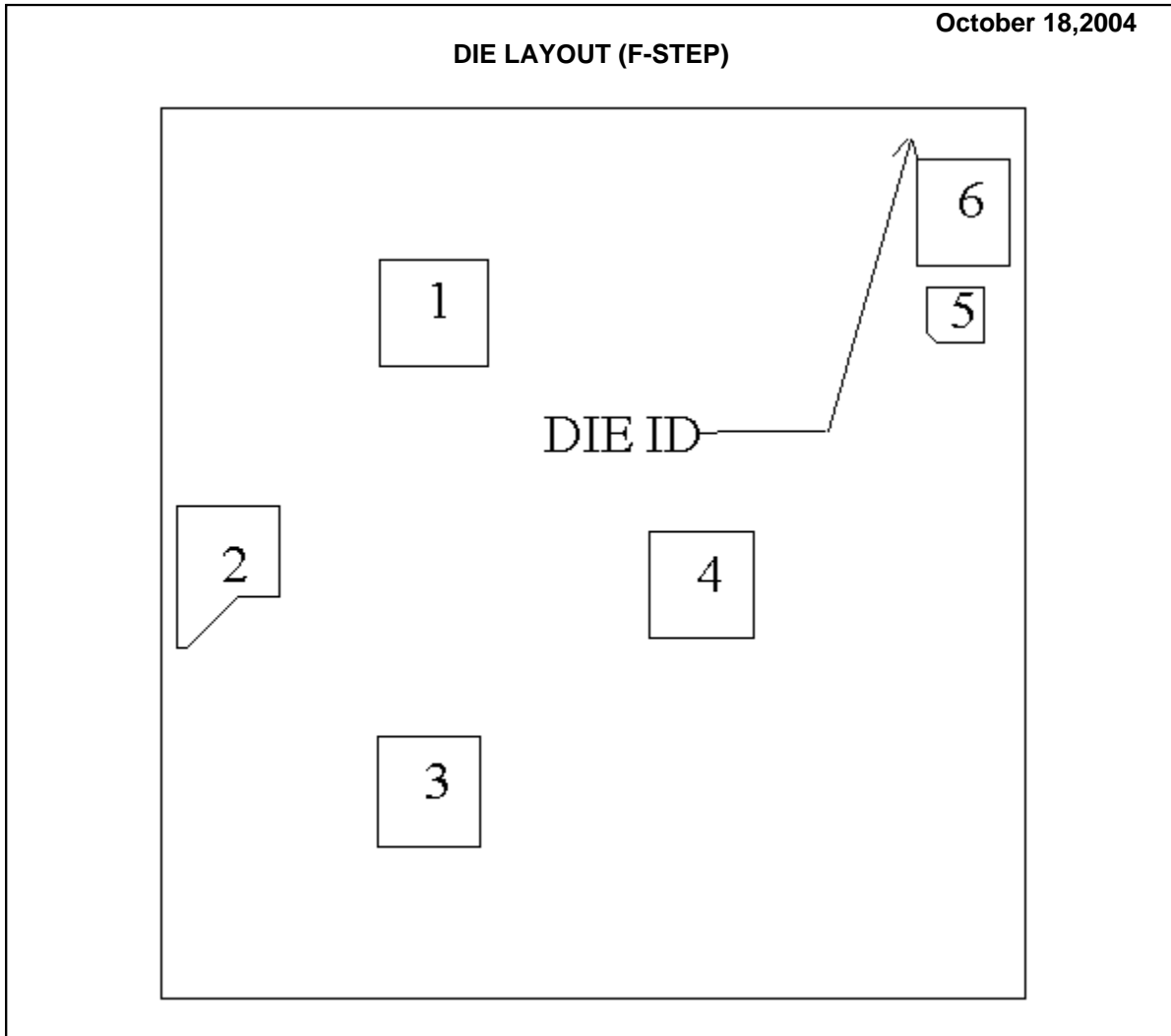


**LM323 MDC MWC**  
**3-AMP, 5-VOLT POSITIVE REGULATOR**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	123F	Bond Pad Opening Size (min)	257 $\mu$ m x 297 $\mu$ m
Die Step	F	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	GOLD BACK
Die Size (Drawn)	2413 $\mu$ m x 2489 $\mu$ m 95.0mils x 98.0mils	Back Side Connection	GND
Thickness	254 $\mu$ m Nominal		
Min Pitch	824 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (F-Step)

(Referenced to die center, coordinates in  $\mu\text{m}$ ) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	XY COORDINATES		PAD SIZE	
		X	Y	X	Y
OUTPUT	1	-445	672	305	x 297
INPUT	2	-1021	-64	284	x 396
OUTPUT	3	-458	-667	287	x 307
INPUT	4	302	-89	295	x 295
NC	5	1011	667	157	x 155
GND	6	1035	953	257	x 295

**LM323 MDC MWC  
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**K**

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